



Features

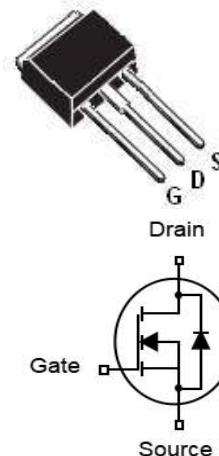
- High ruggedness
- Low RDS(ON)
- Low Gate Charge
- Improved dv/dt Capability
- 100% Avalanche Tested
- 100% EAS Tested



Part ID	Package Type	Marking	Packing
ZT65R1K2	TO-251	ZT65R1K2	4500pcs/Tape

V_{DS}	650	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	1	Ω
I_D	4	A

TO-251



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 30	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650	V	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c = 25^\circ\text{C}$	12	A

Mounted on Large Heat Sink

I_D	Drain Current-Continuous (Note 1)	$T_c = 25^\circ\text{C}$	4	A	
		$T_c = 100^\circ\text{C}$	2.5	A	
P_D		50	W		
$R_{\theta JC}$		2.5	$^\circ\text{C}/\text{W}$		
$R_{\theta JA}$		125	$^\circ\text{C}/\text{W}$		

Drain-Source Avalanche Ratings

EAS	Avalanche Energy, Single Pulsed (Note 3)	45	mJ
E_{AR}	Repetitive Avalanche Energy (Note 2)	5	mJ
dv/dt	MOSFET dv/dt ruggedness (@ $V_{DS}=0\text{~}480$ V)	50	V/ns
dv/dt	Peak diode recovery dv/dt ($V_{DS}=0\text{~}480$ V, $I_{SD} \leq I_D$)	15	V/ns



Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	650	--	--	V
IDSS	Drain to source leakage current	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
		$V_{DS}=520\text{V}, T_J=125^\circ\text{C}$	--	--	50	μA
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 30\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.5	3.5	4.5	V
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=2\text{A}$	--	1	1.2	Ω
G _{fs}	Forward transconductance	$V_{DS}=30\text{V}, I_D=2\text{A}$	--	2.0	--	S
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
Ciss	Input Capacitance	$V_{DS}=200\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	179	--	pF
Coss	OutputCapacitance		--	18	--	pF
Crss	ReverseTransferCapacitance		--	1.2	--	pF
Rg	Gate Resistance	f=1MHz	--	28	--	Ω
Qg	Total Gate Charge	$V_{DS}=520\text{V}, I_D=4\text{A}, V_{GS}=10\text{V}, I_G=1\text{mA}$	--	9.2	--	nC
Qgs	Gate-SourceCharge		--	0.9	--	nC
Qgd	Gate-DrainCharge		--	6.3	--	nC
Switching Characteristics						
Td(on)	Turn-on Delay Time	$V_{DS}=325\text{V}, I_D=4\text{A}, R_G=10\Omega, V_{GS}=10\text{V}$	--	8.9	--	ns
Tr	Turn-on Rise Time		--	26.8	--	ns
Td(off)	Turn-Off Delay Time		--	8.9	--	ns
Tf	Turn-Off Fall Time		--	22.7	--	ns
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
VSD	Forward on voltage	$I_S=8\text{A}, V_{GS}=0\text{V}$	--	--	1.4	V
Trr	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_S=8\text{A}, V_{GS}=0\text{V}, di/dt=100\text{A}/\mu\text{s}$	--	197	--	ns
Qrr	Reverse Recovery Charge		--	1.2	--	uC
Irrm	Peak reverse recovery current		--	10.5	--	A

Notes:

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
- 3 . L = 40mH, I_{AS} = 1.5A, V_{DD} = 100V, R_G=25Ω, Starting at T_J = 25°C

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

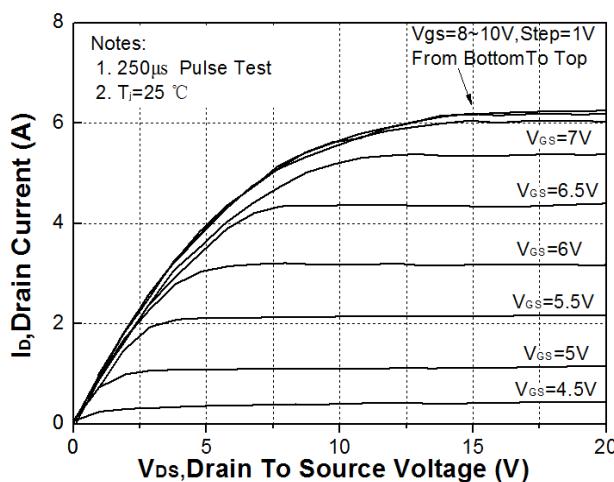


Fig 1. Output characteristics ($T_J=25^\circ\text{C}$)

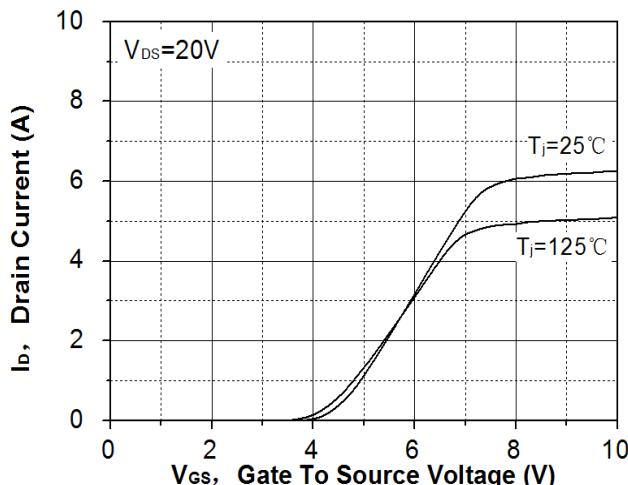


Fig 2. Transfer characteristics

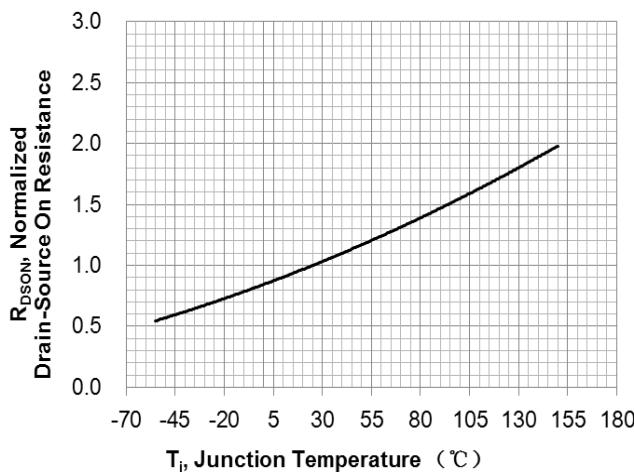


Fig 3. $R_{DS(ON)}$ vs Junction Temperature

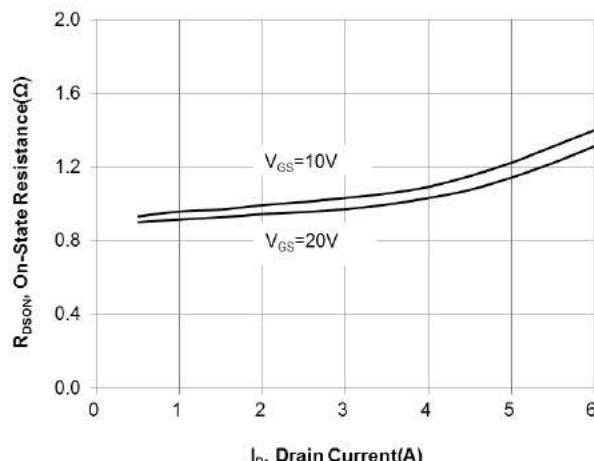


Fig 4. Drain-source on-state resistance

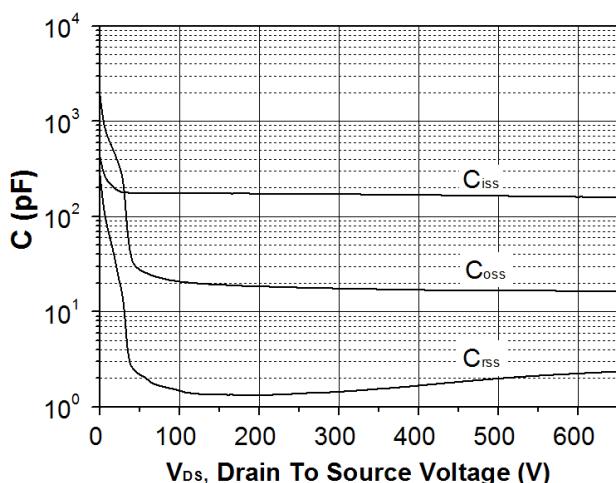


Fig 5. Capacitance Characteristics

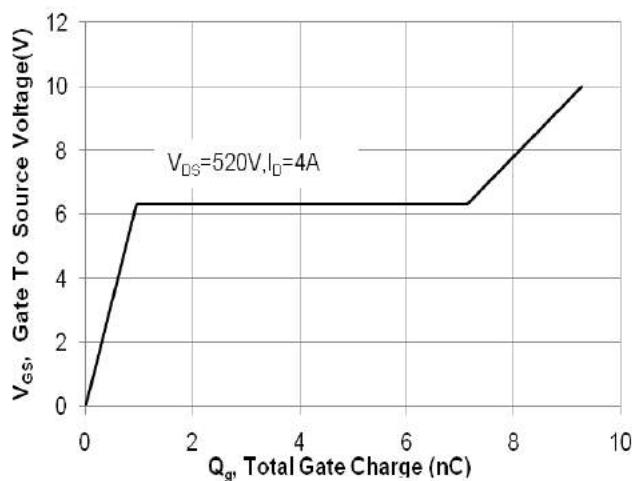


Fig 6. Gate charge characteristics

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

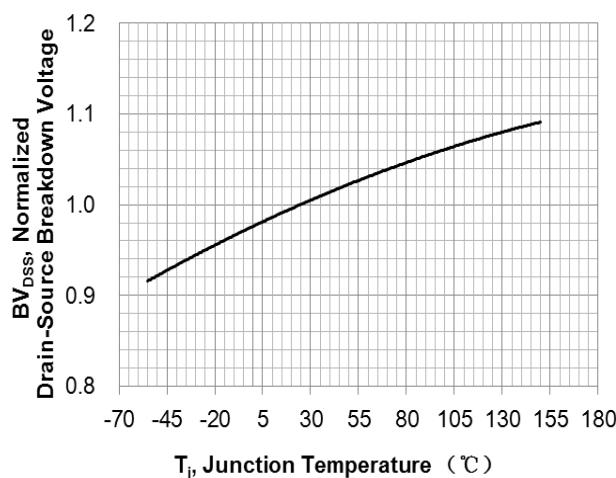


Fig 7. BV_{DSS} vs Junction Temperature

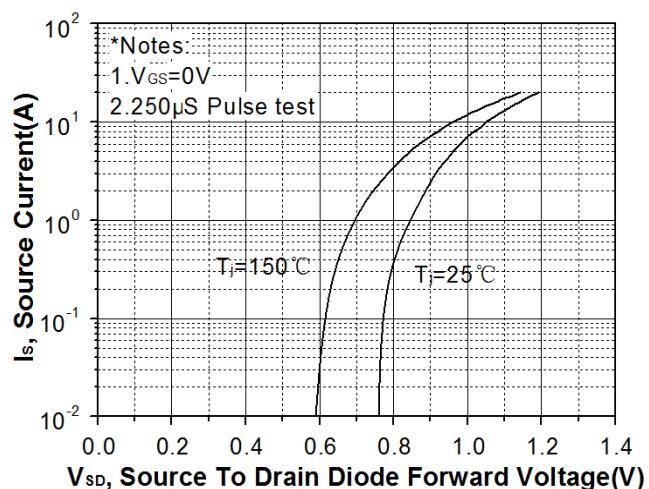


Fig 8 . Forward characteristics of reverse diode

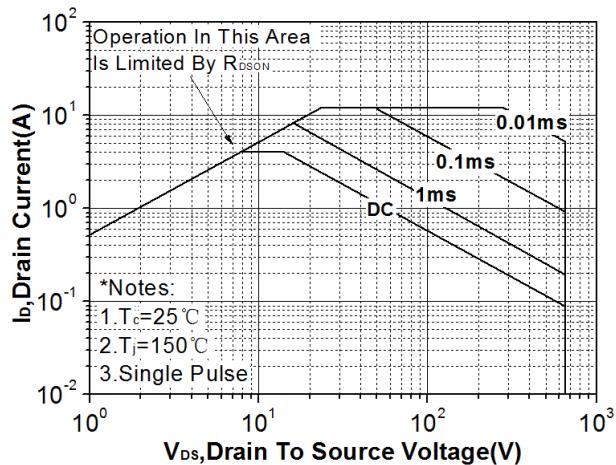


Fig 9. Safe operating area(TO-252)

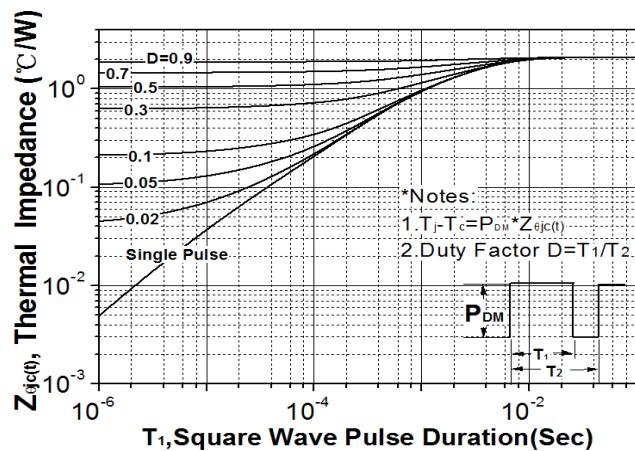


Fig 10. Transient thermal impedance (TO-252)

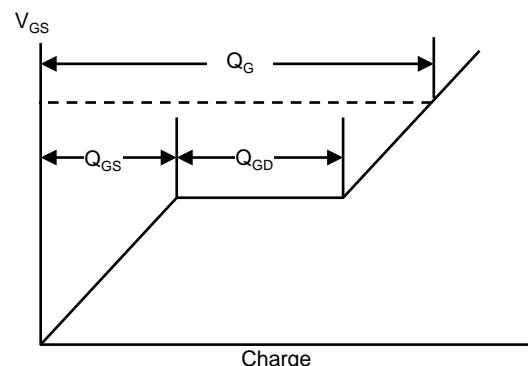
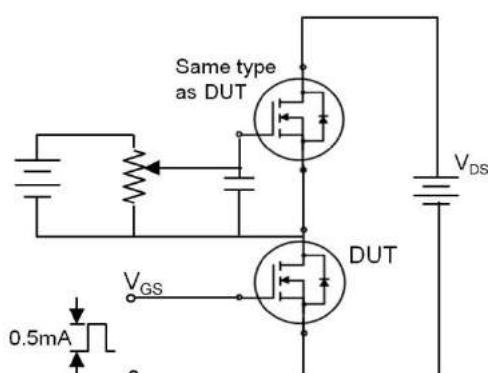


Fig A. Gate charge test circuit & waveform

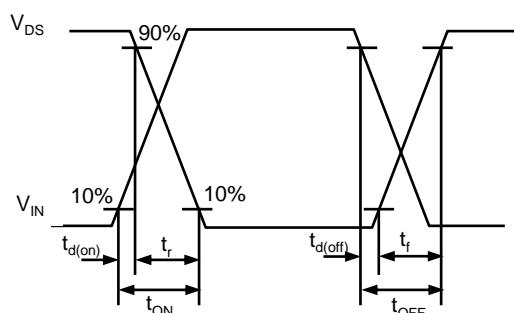
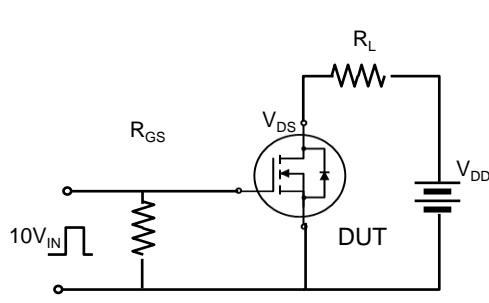


Fig B. Switching time test circuit & waveform

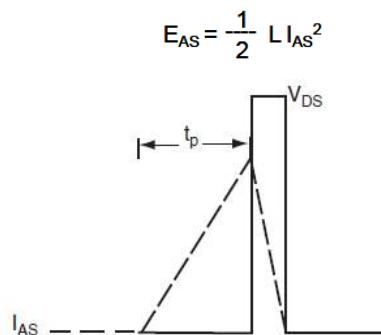
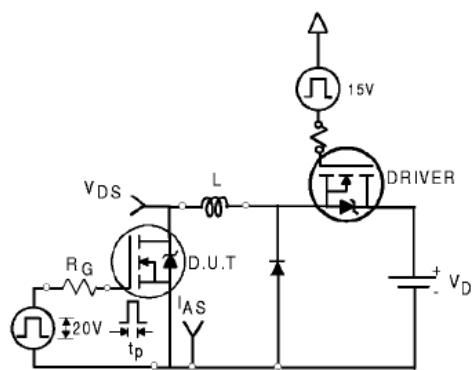


Fig C. Unclamped Inductive switching test circuit & waveform

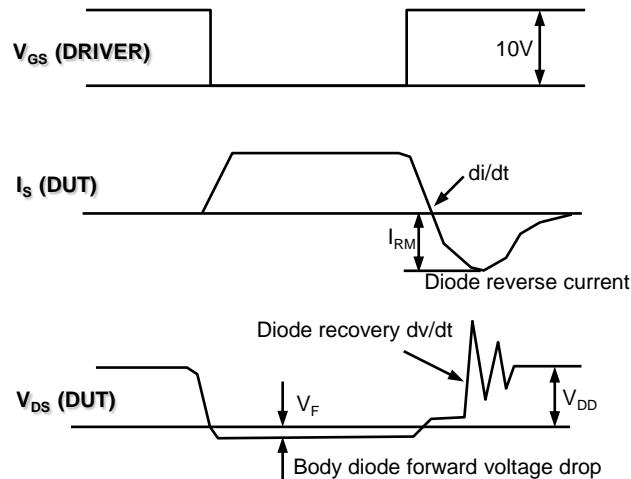
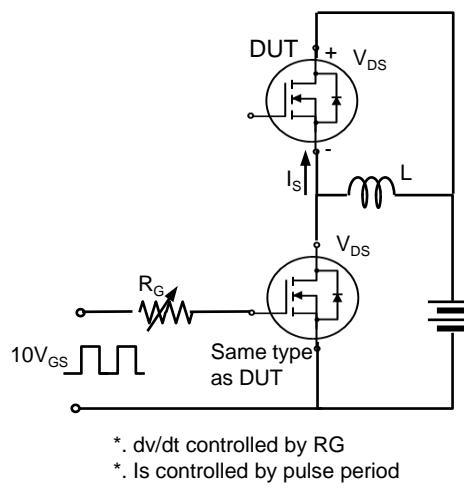
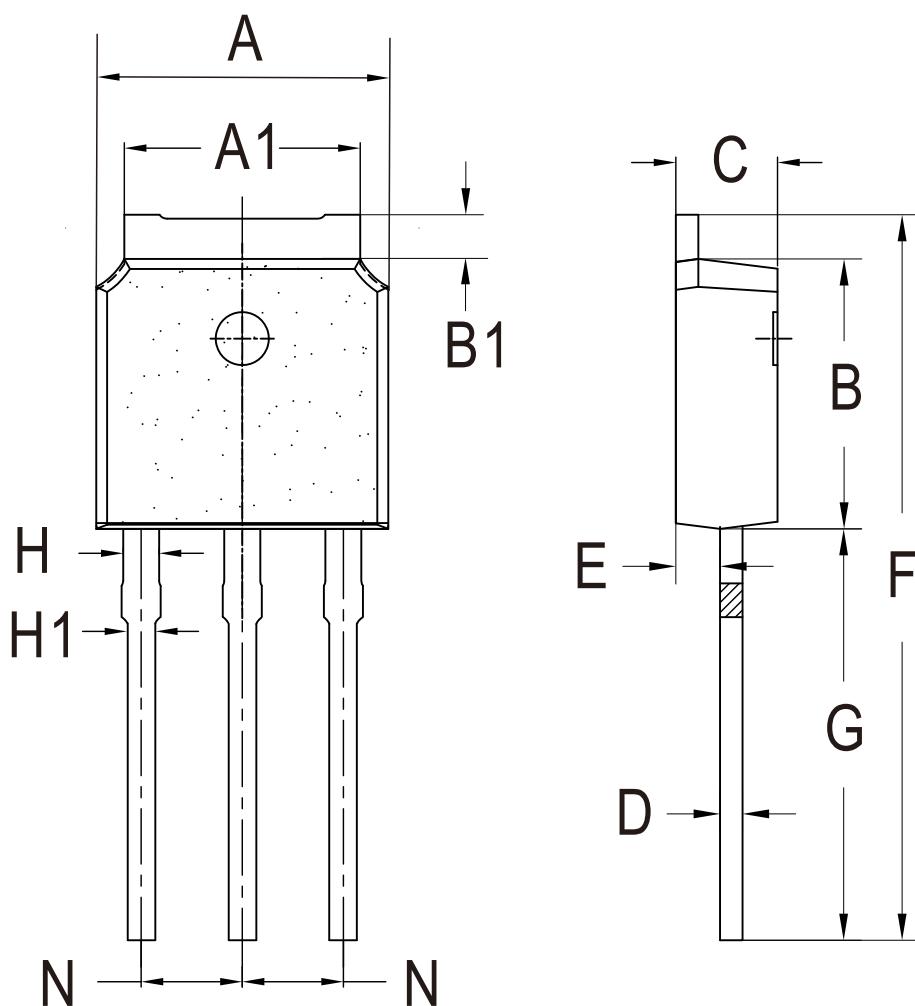


Fig D. Peak diode recovery dv/dt test circuit & waveform



TO-251-3L Package Information



Symbol	Millimeters		Symbol	Millimeters	
	Min.	Max.		Min.	Max.
A	6.40	6.80	E	0.90	1.10
A1	5.20	5.50	F	16.10	16.70
B	5.90	6.30	G	9.20	9.60
B1	0.95	1.25	H	0.70	0.90
C	2.10	2.50	H1	0.50	0.70
D	0.40	0.60	N	2.20	2.40

Customer Service

Sales and Service:

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